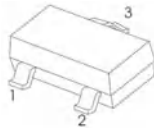
FEATURES

- Ideally suited for automatic insertion
- For switching and AF amplifier applications

SOT-23



1.BASE
2.EMITTER
3.COLLECTOR

1 x

Type number	Marking code
BC846A	1A
BC846B	1B
BC847A	1E
BC847B	1F
BC847C	1G
BC848A	1J
BC848B	1K
BC848C	1L

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

MAXIMUM RATINGS (Ta=25℃ unless otherwise noted)

Parameter		Symbol	Value	Unit
Collector–Base Voltage	BC846 BC847 BC848	V_{CBO}	80 50 30	V
Collector–Emitter Voltage	BC846 BC847 BC848	V_{CEO}	65 45 30	V
Emitter–Base Voltage		V_{EBO}	6	V
Collector Current — Continuous		I_C	0.1	A
Collector Power Dissipation		P_C	200	mW
Thermal Resistance From JunctionTo Ambient		R_{thJA}	625	℃/W
Junction Temperature		T_J	150	℃
Storage Temperature		T_{stg}	-55~+150	℃

ELECTRICAL CHARACTERISTICS (TA = 25°C unless otherwise noted.)

Parameter		Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	BC846 BC847 BC848	V_{CBO}	I_C =10uA, I_E = 0	80 50 30			V
Collector-emitter breakdown voltage	BC846 BC847 BC848	V_{CEO}	I_C =10mA, I_B = 0	65 45 30			V
Emitter-base breakdown voltage		V_{EBO}	I_E =10uA, I_C = 0	6			V
Collector cut-off current	BC846 BC847 BC848	I_{CBO}	V_{CB} =70V, I_E = 0 V_{CB} =50V, I_E = 0 V_{CB} =30V, I_E = 0			0.1	uA
Collector cut-off current	BC846 BC847 BC848	I_{CEO}	V_{CE} =60V, I_B =0 V_{CE} =45V, I_B =0 V_{CE} =30V, I_B =0			0.1	uA
Emitter cut-off current		I_{EBO}	V_{EB} =5V, I_C = 0			0.1	uA
DC current gain	BC846A,847A,848A BC846B,847B,848B BC847C,BC848C	h_{FE}	V_{CE}=5V,I_C=2mA	110 200 420		220 450 800	
Collector-emitter saturation voltage		$V_{CE(sat)}$	I_C =100mA, I_B =5mA			0.5	V
Base-emitter saturation voltage		$V_{BE(sat)}$	I_C =100mA, I_B =5mA			1.1	V
Transition frequency		f_T	V_{CE} =5V, I_C =10mA,f =100MHz	100			MHz
Collector output capacitance		C_{ob}	V_{CB} =10V, f =1MHz			4.5	pF

RATING AND CHARACTERISTIC CURVES

Fig.1 Static characteristics

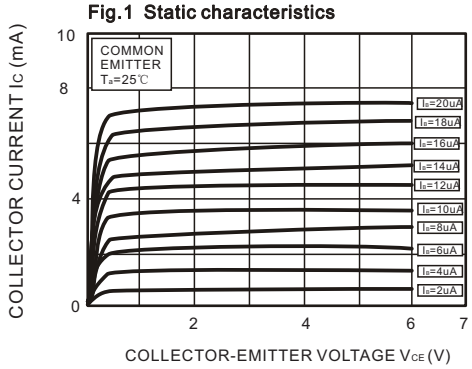


Fig.2 P_C —— T_a

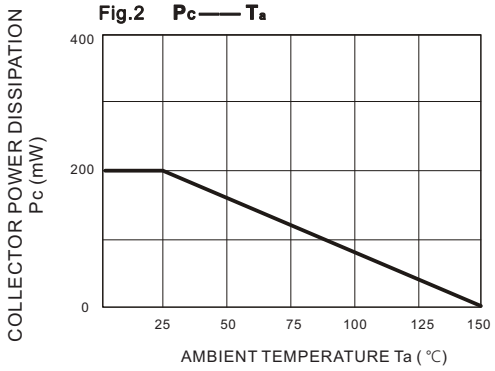


Fig.3 C_{ob} / C_{ib} —— V_{CB} / V_{EB}

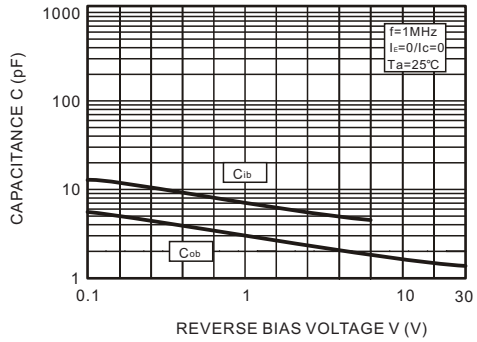


Fig.4 V_{CEsat} —— Ic

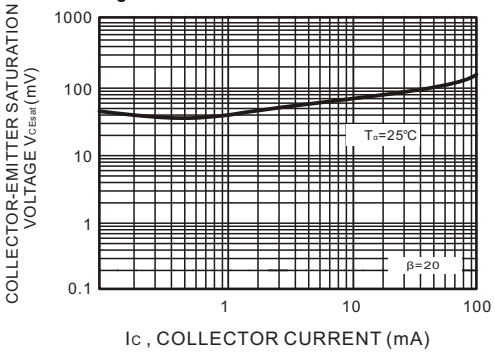


Fig.5 h_{FE}--Ic

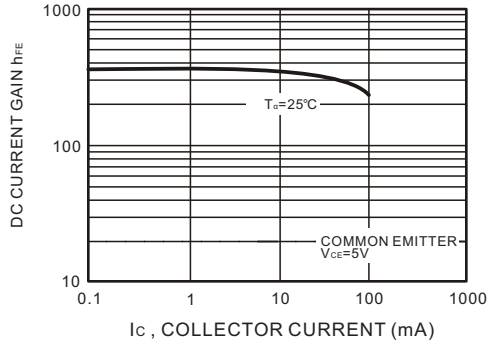


Fig.6 V_{BEsat} —— Ic

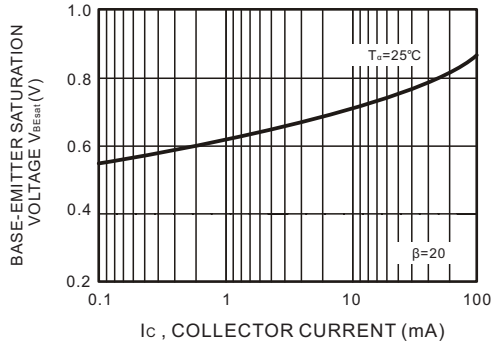


Fig.7 Ic —— V_{BE}

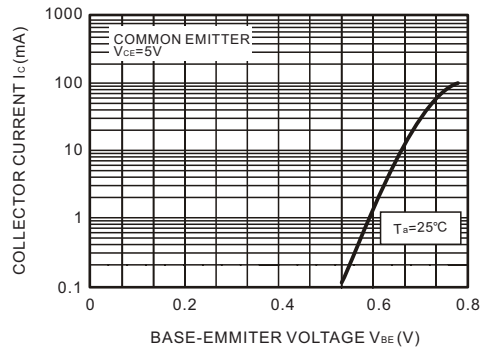
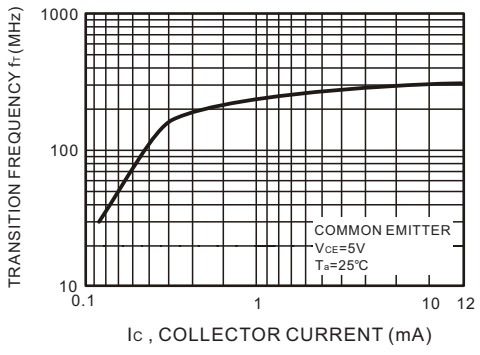


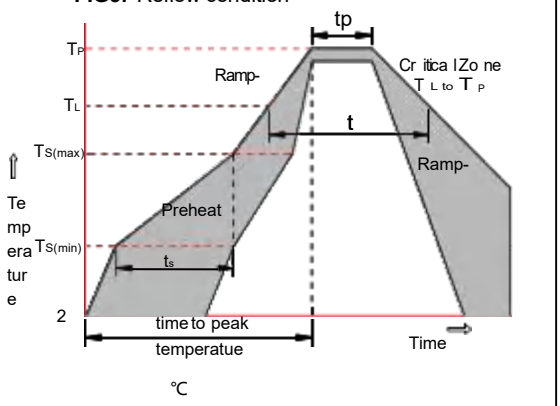
Fig.8 f_T ——Ic



Soldering parameters

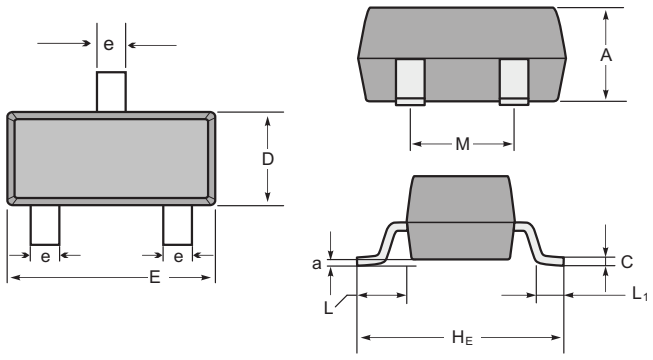
Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃ of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃

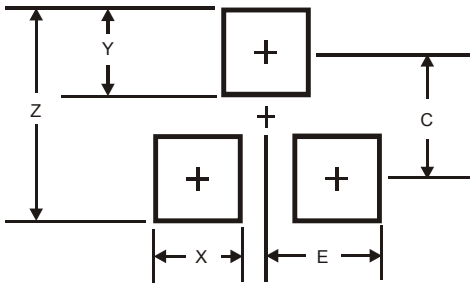
FIG5: Reflow condition



Package Dimensions & Suggested Pad Layout

SOT23





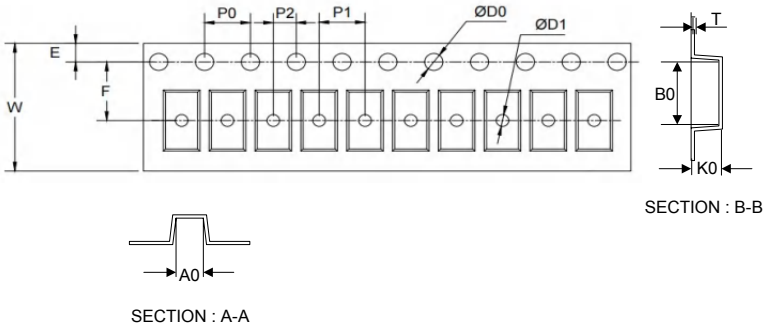
SOT-23 mechanical data

UNIT		A	C	D	E	H_E	e	M	L	L_1	a
mm	max	1.1	0.15	1.4	3.0	2.6	0.5	1.95	0.55 (ref)	0.36 (ref)	0.0
	min	0.9	0.08	1.2	2.8	2.2	0.3	1.7			0.15
mil	max	43	6	55	118	102	20	77	22 (ref)	14 (ref)	0.0
	min	35	3	47	110	87	12	67			6

Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

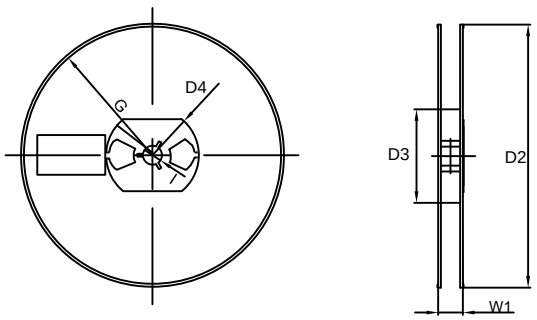
Tape & rell specification

Tape



Symbol	Dimension (mm)
P0	4.00±0.10
P1	4.00±0.10
P2	2.00±0.10
D0	1.55±0.10
D1	1.05±0.10
E	1.55±0.10
F	3.60±0.10
W	8.00±0.10
A0	3.80±0.20
B0	3.25±0.20
K0	1.45±0.10
T	0.25±0.05

7” Reel



D2	178.0±3.0
D3	55Min.
D4	R24.0±3.0
G	R82.0±3.0
I	13.0±2.0
W1	11.0±3.0

Quantity: 3000PCS